

encapsulation by molding; and

at least one geometric area of material alteration formed in the conductive material forming the lead frame, the area located substantially at either frame end, wherein a user accesses the strip of adhesive material through utilization of the material alteration for the purpose of removing the adhesive material from the surface of the lead frame.

2. The lead frame apparatus of claim 1, wherein the adhesive material is thermal resist tape.
3. The lead frame apparatus of claim 2, wherein the thermal resist tape after application to the frame is dimensionally equal to the overall dimensions of the frame.
4. The lead frame apparatus of claim 3, wherein the material alteration is a perforated tab.
5. The lead frame apparatus of claim 4, wherein the geometric area defining the material alteration is rectangular.
6. The lead frame apparatus of claim 5, wherein the material alteration spans the entire width of the lead frame.
7. The lead frame apparatus of claim 5, wherein etching before application of the adhesive material produces the material alteration.
8. The lead frame apparatus of claim 3, wherein the material alteration is characterized by an absence of material.
9. A lead frame apparatus of claim 8, wherein a material removal process

performed before application of the adhesive material produces the material alteration.

10. The lead frame apparatus of claim 9, wherein the geometric area defining the material alteration is rectangular.

11. The lead frame apparatus of claim 9, wherein the geometric area defining the material alteration is annular.

12. The lead frame apparatus of claim 4, wherein the geometric area defining the material alteration is annular.

13. The lead frame apparatus of claim 4, wherein the material alteration is defined by an array of separated geometric areas.

14. The lead frame apparatus of claim 9, wherein the material alteration is defined by an array of separated geometric areas.

15. The lead frame apparatus of claim 1, wherein heat is used during the process of removing the adhesive material from the lead frame.

16. Lead frame apparatus of claim 15, wherein the heat source is a hotplate having a length dimension extending at least the overall length dimension of the lead frame.